

DCVD PROCESS: OPTIMIZATION & TROUBLESHOOTING

Who should attend?

This course is designed for those individuals in the semiconductor industry who require the knowledge to optimize and troubleshoot process problems on DCVD tools.

Course Benefits

Reduce time to recover from wafer processing faults.

Increase wafer processing yield.

Increase Mean Wafers Between Clean (MWBC).

Decrease number of defects per wafer.

Course Objectives

- Understand the DCVD principles and applications.
- Describe the PE-silane and PE-TEOS processes and their applications.
- Predict the PE-silane and PE-TEOS process trends and apply them in troubleshooting.

Course Modules

1. *Overview*
2. *Safety*
3. *Silane Oxide*
4. *Silane Nitride*
5. *Silane OxyNitride*
6. *PE-TEOS*
7. *PSG*
8. *Troubleshooting*

Registration Information

Prerequisites:

- *DCVD Process: Concepts & Measurements eLearning (TRNWEB-13)*
OR
- *DCVD Process: Concepts & Measurements (TRNPRC-30)*

Course Length: 4 Hours

Course Type: Web-based Training

Course Number: TRNWEB-121

Customers: To enroll or for more information on our products and services, please call our registrar at one of the numbers below or go to www.appliedtraining.com.

- 1-800-468-8888, option 4 (United States)
- 1-512-272-0027 (International)

Applied Materials Employees: Please go to our intranet site, <http://GTT>, or call the 800 number above.

Computer System Requirements:

Attending this course requires a Windows 98, NT, 2000 or XP computer using Internet Explorer 5.5 or higher. 128MB RAM or higher and high-speed Internet access is also highly recommended.